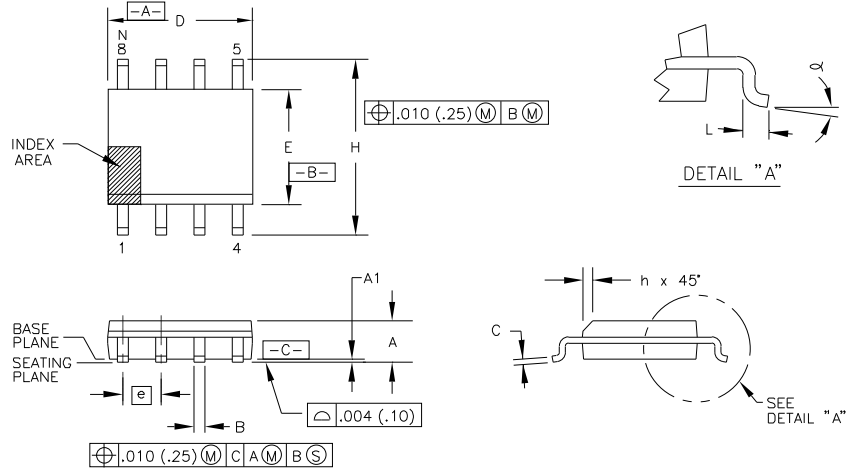


Package Number 182 - 8-Lead SOIC



DIM	INCHES		MILLIMETERS		N	E
	MIN.	MAX.	MIN.	MAX.		
A	.0532	.0688	1.35	1.75		
A1	.004	.0098	0.10	0.23		
B	.013	.020	0.33	0.51	7	
C	.0075	.0098	0.20	0.25		
D	.189	.1968	4.80	4.98	2	
E	.1497	.1574	3.80	4.00	3	
e	.050	BASIC	1.27	BASIC		
H	.2284	.244	5.80	6.20		
h	.0099	.0196	0.25	0.50	4	
L	.016	.050	0.41	1.27	5	
N	8		8		6	
alpha	0°	8°	0°	8°		

NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
- DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED .006 IN. (0.15 mm) PER SIDE.
- DIMENSION E DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED .010 IN. (0.25 mm) PER SIDE.
- THE CHAMFER ON THE BODY IS OPTIONAL. IF IT IS NOT PRESENT,

A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS-HATCHED AREA.

- L IS THE LENGTH OF TERMINAL FOR SOLDERING TO A SUBSTRATE.
- N IS THE NUMBER OF TERMINAL POSITIONS.
- THE LEAD WIDTH B, AS MEASURED .014 IN. (0.36 mm) OR GREATER ABOVE THE SEATING PLANE, SHALL NOT EXCEED A MAXIMUM VALUE OF .024 IN. (0.61 mm).
- LEAD TO LEAD COPLANARITY SHALL BE LESS THAN .004 IN. (0.10 mm) FROM SEATING PLANE.

PACKAGE NUMBER: ZZ182 REV.: H
JEDEC NUMBER: MS-012-AA



PACKAGE DRAWING

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